

September 1997 - Revised August 2003

## High-Speed CMOS Logic Dual 4-Stage Binary Counter

### Features

- Fully Static Operation
- Buffered Inputs
- Common Reset
- Negative-Edge Clocking
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The 'HC393 and 'HCT393 are 4-stage ripple-carry binary counters. All counter stages are master-slave flip-flops. The state of the stage advances one count on the negative transition of each clock pulse; a high voltage level on the MR line resets all counters to their zero state. All inputs and outputs are buffered.

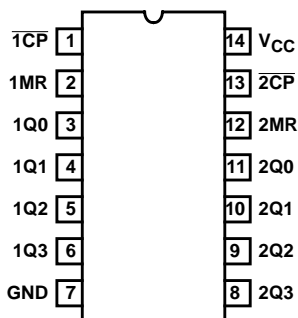
### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC393F3A	-55 to 125	14 Ld CERDIP
CD54HCT393F3A	-55 to 125	14 Ld CERDIP
CD74HC393E	-55 to 125	14 Ld PDIP
CD74HC393M	-55 to 125	14 Ld SOIC
CD74HC393MT	-55 to 125	14 Ld SOIC
CD74HC393M96	-55 to 125	14 Ld SOIC
CD74HCT393E	-55 to 125	14 Ld PDIP
CD74HCT393M	-55 to 125	14 Ld SOIC
CD74HCT393MT	-55 to 125	14 Ld SOIC
CD74HCT393M96	-55 to 125	14 Ld SOIC

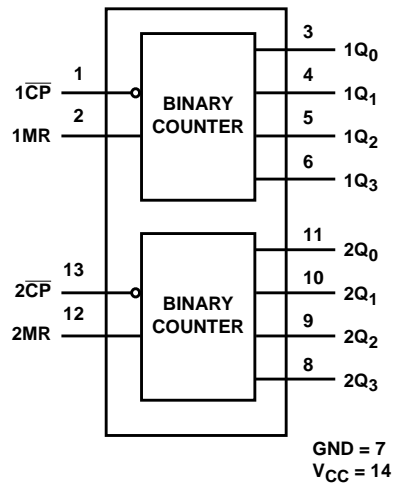
NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

### Pinout

CD54HC393, CD54HCT393  
(CERDIP)  
CD74HC393, CD74HCT393  
(PDIP, SOIC)  
TOP VIEW



## Functional Diagram



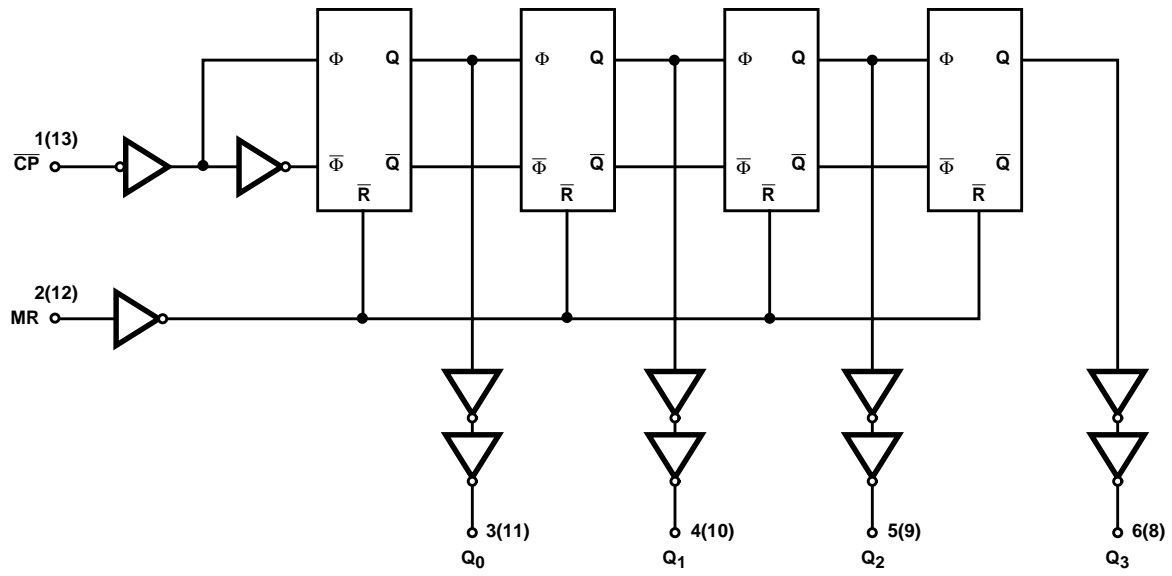
TRUTH TABLE

CP COUNT	OUTPUTS			
	Q <sub>0</sub>	Q <sub>1</sub>	Q <sub>2</sub>	Q <sub>3</sub>
0	L	L	L	L
1	H	L	L	L
2	L	H	L	L
3	H	H	L	L
4	L	L	H	L
5	H	L	H	L
6	L	H	H	L
7	H	H	H	L
8	L	L	L	H
9	H	L	L	H
10	L	H	L	H
11	H	H	L	H
12	L	L	H	H
13	H	L	H	H
14	L	H	H	H
15	H	H	H	H

CP COUNT	MR	OUTPUT
↑	L	No Change
↓	L	Count
X	H	L L L L

H = High Voltage Level, L = Low Voltage Level, X = Don't Care,  
 ↑ = Transition from Low to High Level, ↓ = Transition from High to Low.

**Logic Diagram**



# CD54HC393, CD74HC393, CD54HCT393, CD74HCT393

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 1)	$\theta_{JA}$ ( $^{\circ}C/W$ )
E (PDIP) Package	80
M (SOIC) Package	86
Maximum Junction Temperature	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$ (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range ( $T_A$ )	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types	.2V to 6V
HCT Types	4.5V to 5.5V
DC Input or Output Voltage, $V_I$ , $V_O$	0V to $V_{CC}$
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
-			-	-	-	-	-	-	-	-	V	
-			4.5	3.98	-	-	3.84	-	3.7	-	V	
-5.2			6	5.48	-	-	5.34	-	5.2	-	V	
High Level Output Voltage TTL Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
4			4.5	-	-	0.26	-	0.33	-	0.4	V	
5.2			6	-	-	0.26	-	0.33	-	0.4	V	
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
4			4.5	-	-	0.26	-	0.33	-	0.4	V	
5.2			6	-	-	0.26	-	0.33	-	0.4	V	
Low Level Output Voltage TTL Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
4			4.5	-	-	0.26	-	0.33	-	0.4	V	
5.2			6	-	-	0.26	-	0.33	-	0.4	V	
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	µA

**CD54HC393, CD74HC393, CD54HCT393, CD74HCT393**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

INPUT	UNIT LOADS
nCP	0.4
nMR	1

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

**Prerequisite for Switching Specifications**

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES										
Maximum Clock Frequency	f <sub>MAX</sub>	2	6	-	-	5	-	4	-	MHz
		4.5	30	-	-	24	-	20	-	MHz
		6	35	-	-	28	-	24	-	MHz
Clock Pulse Width	t <sub>W</sub>	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns

**CD54HC393, CD74HC393, CD54HCT393, CD74HCT393**

**Prerequisite for Switching Specifications (Continued)**

PARAMETER	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Reset Recovery Time	t <sub>REC</sub>	2	5	-	-	5	-	5	-	ns
		4.5	5	-	-	5	-	5	-	ns
		6	5	-	-	5	-	5	-	ns
Reset Pulse Width	t <sub>W</sub>	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns

**HCT TYPES**

Maximum Clock Frequency	f <sub>MAX</sub>	4.5	27	-	-	22	-	18	-	MHz
Clock Pulse Width	t <sub>W</sub>	4.5	19	-	-	24	-	29	-	ns
Reset Recovery Time	t <sub>REC</sub>	4.5	5	-	-	5	-	5	-	ns
Reset Pulse Width	t <sub>W</sub>	4.5	16	-	-	20	-	24	-	ns

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay Time (Figure 1)  nCP to nQ <sub>0</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	150	-	190	-	225	ns
			4.5	-	-	30	-	38	-	59	ns
		C <sub>L</sub> = 15pF	5	-	12	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	26	-	33	-	50	ns
nCP to nQ <sub>1</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	190	-	245	-	295	ns
			4.5	-	-	38	-	49	-	59	ns
			6	-	-	33	-	42	-	50	ns
nCP to nQ <sub>2</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	240	-	300	-	360	ns
			4.5	-	-	48	-	60	-	72	ns
			6	-	-	41	-	51	-	61	ns
nCP to nQ <sub>3</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	285	-	355	-	430	ns
			4.5		-	57	-	71	-	86	ns
			6	-	-	48	-	60	-	73	ns
MR to Q <sub>n</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	135	-	170	-	205	ns
			4.5	-	-	27	-	34	-	41	ns
		C <sub>L</sub> = 15pF	5	-	11	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	23	-	29	-	35	ns
Output Transition Time (Figure 1)	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	C <sub>IN</sub>	C <sub>L</sub> = 50pF	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	20	-	-	-	-	-	pF

# **CD54HC393, CD74HC393, CD54HCT393, CD74HCT393**

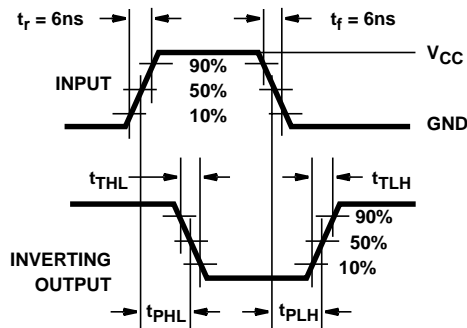
## **Switching Specifications** Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES											
Propagation Delay Time (Figure 1)	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	32	-	40	-	48	ns
n $\overline{C\overline{P}}$ to nQ <sub>0</sub>		C <sub>L</sub> = 15pF	5	-	13	-	-	-	-	-	ns
n $\overline{C\overline{P}}$ to nQ <sub>1</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	44	-	55	-	66	ns
n $\overline{C\overline{P}}$ to nQ <sub>2</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	50	-	63	-	75	ns
n $\overline{C\overline{P}}$ to nQ <sub>3</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	62	-	78	-	93	ns
MR to Q <sub>n</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	32	-	40	-	48	ns
		C <sub>L</sub> = 15pF	5	-	13	-	-	-	-	-	ns
Output Transition	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C <sub>IN</sub>	C <sub>L</sub> = 15pF	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C <sub>PD</sub>	C <sub>L</sub> = 15pF	5	-	21	-	-	-	-	-	pF

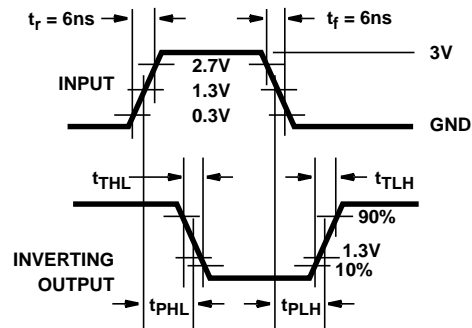
NOTES:

- $C_{PD}$  is used to determine the dynamic power consumption, per stage.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## **Test Circuits and Waveforms**



**FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



**FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8989001CA	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	5962-8989001CA CD54HCT393F3A	<a href="#">Samples</a>
CD54HC393F3A	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	8410001CA CD54HC393F3A	<a href="#">Samples</a>
CD54HCT393F	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	CD54HCT393F	<a href="#">Samples</a>
CD54HCT393F3A	ACTIVE	CDIP	J	14	1	TBD	SNPB	N / A for Pkg Type	-55 to 125	5962-8989001CA CD54HCT393F3A	<a href="#">Samples</a>
CD74HC393E	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC393E	<a href="#">Samples</a>
CD74HC393M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC393M	<a href="#">Samples</a>
CD74HC393M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC393M	<a href="#">Samples</a>
CD74HC393M96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC393M	<a href="#">Samples</a>
CD74HC393MT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC393M	<a href="#">Samples</a>
CD74HCT393E	ACTIVE	PDIP	N	14	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT393E	<a href="#">Samples</a>
CD74HCT393M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT393M	<a href="#">Samples</a>
CD74HCT393M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT393M	<a href="#">Samples</a>
CD74HCT393ME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT393M	<a href="#">Samples</a>
CD74HCT393MT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT393M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.



<sup>(2)</sup> **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF CD54HC393, CD54HCT393, CD74HC393, CD74HCT393 :**

● Catalog: [CD74HC393](#), [CD74HCT393](#)

● Military: [CD54HC393](#), [CD54HCT393](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC393M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74HC393MT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74HCT393M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74HCT393MT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC393M96	SOIC	D	14	2500	367.0	367.0	38.0
CD74HC393MT	SOIC	D	14	250	210.0	185.0	35.0
CD74HCT393M96	SOIC	D	14	2500	367.0	367.0	38.0
CD74HCT393MT	SOIC	D	14	250	210.0	185.0	35.0

**J 14**

## GENERIC PACKAGE VIEW

**CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

**J0014A****PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



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D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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